
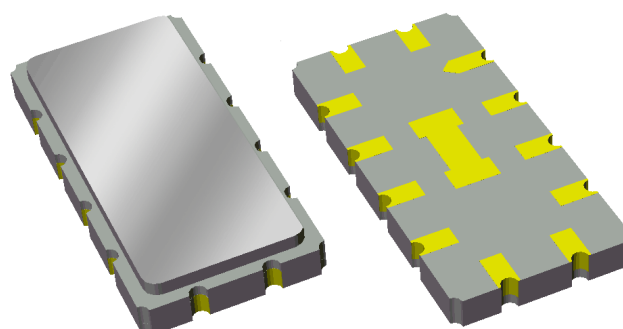


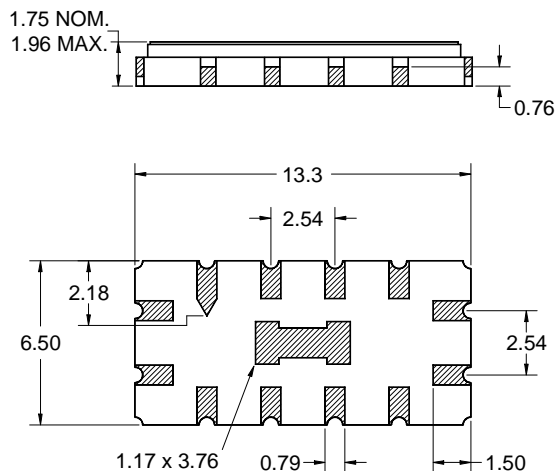
## Features

- Usable bandwidth of 700 kHz
- Low loss
- High attenuation
- Single-ended operation, 50  $\Omega$
- Ceramic Surface Mount Package (SMP)
- Hermetic
- RoHS compliant (2002/95/EC), Pb-free 



## Package

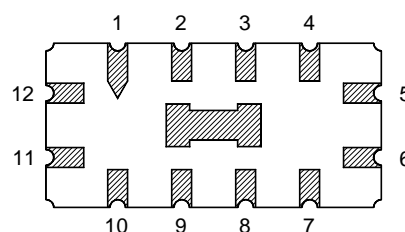
Surface Mount 13.30 x 6.50 x 1.75 mm  
SMP-53B



## Pin Configuration

Bottom View

This package includes a center pad.  
Soldering of the center pad to PCB is not recommended and not required.



### Single-ended Configuration

Pin No.	Description
5	Output
11	Input
1,2,3,4,6	Case ground
7,8,9,10,12	Case ground

Dimensions shown are nominal in millimeters  
All tolerances are  $\pm 0.15$  mm except overall  
length and width  $\pm 0.10$  mm

Body:  $Al_2O_3$  ceramic

Lid: Kovar, Ni plated

Terminations: Au plating 0.5 - 1.0  $\mu$ m,  
over a 2 - 6  $\mu$ m Ni plating

## Electrical Specifications <sup>(1)</sup>

Operating Temperature Range: <sup>(2)</sup> -10 to +85 °C

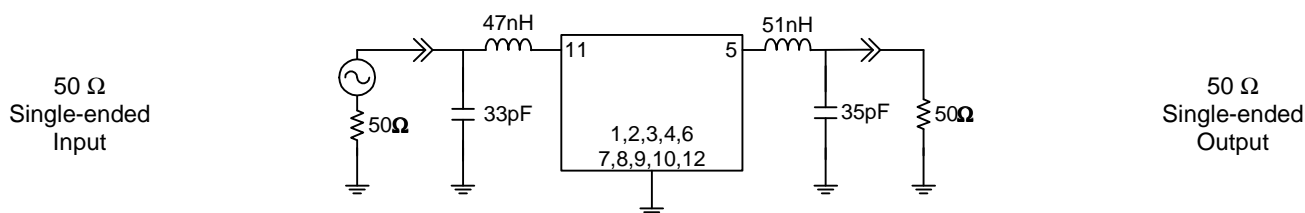
Parameter <sup>(3)</sup>	Minimum	Typical <sup>(4)</sup>	Maximum	Unit
Center Frequency, $F_o$	-	211	-	MHz
Minimum Insertion Loss at $F_o$		5.75	8.0	dB
3 dB Lower Bandedge <sup>(5)</sup>	-	210.56	210.6	MHz
3 dB Upper Bandedge <sup>(5)</sup>	211.4	211.5	-	MHz
Attenuation at $F_o \pm 630$ kHz	6	8.1	-	dB
Attenuation at $F_o \pm 1$ MHz	10	28.4	-	dB
Absolute Delay	-	1.383	-	$\mu$ s
Group Delay Ripple 210.85 - 211.15 MHz	-	215	250	ns
Relative Attenuation <sup>(5)</sup>				
131 - 209 MHz	30	46.6	-	dB
213 - 291 MHz	30	46.6	-	dB
291 - 2000 MHz	40	70	-	dB
Optimal Source Impedance <sup>(6)</sup>	-	50	-	$\Omega$
Optimal Load Impedance <sup>(6)</sup>	-	50	-	$\Omega$

### Notes:

1. All specifications are based on the TriQuint test circuit shown below
2. In production, devices will be tested at room temperature to a guardbanded specification to ensure electrical compliance over temperature
3. Electrical margin has been built into the design to account for the variations due to temperature drift and manufacturing tolerances
4. Typical values are based on average measurements at room temperature
5. Relative to minimum insertion loss at  $F_o$
6. This is the optimum impedance in order to achieve the performance shown

### Test Circuit:

Actual matching values may vary due to PCB layout and parasitics



## Electrical Specifications <sup>(1)</sup>

Operating Temperature Range: <sup>(2)</sup> -40 to +85 °C

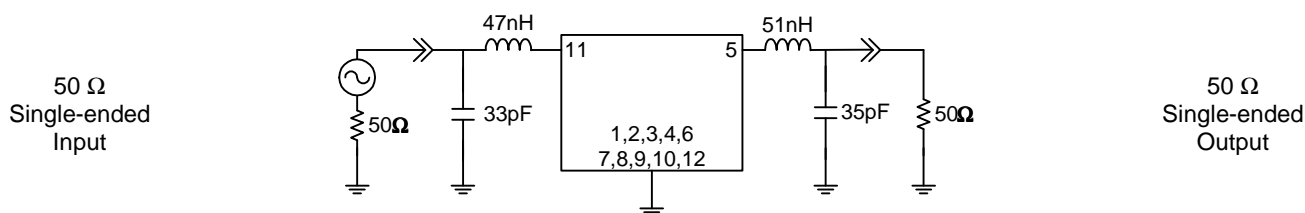
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Relative Attenuation <sup>(5)</sup>				
131 - 209 MHz	30	46.6	-	dB
213 - 291 MHz	30	46.6	-	dB
291 - 2000 MHz	40	70	-	dB
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### Notes:

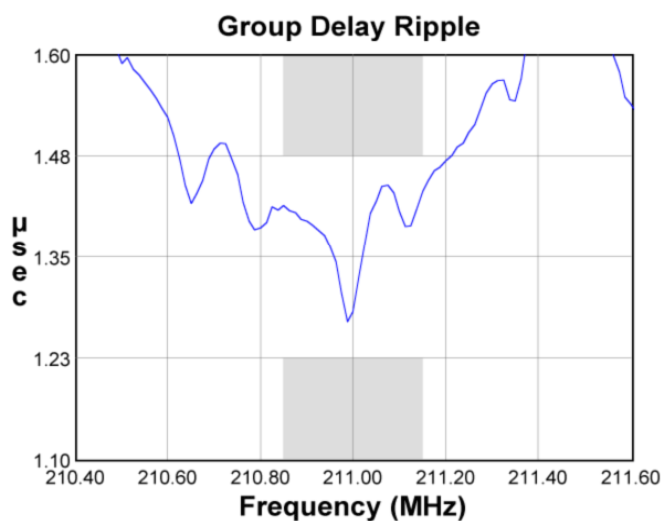
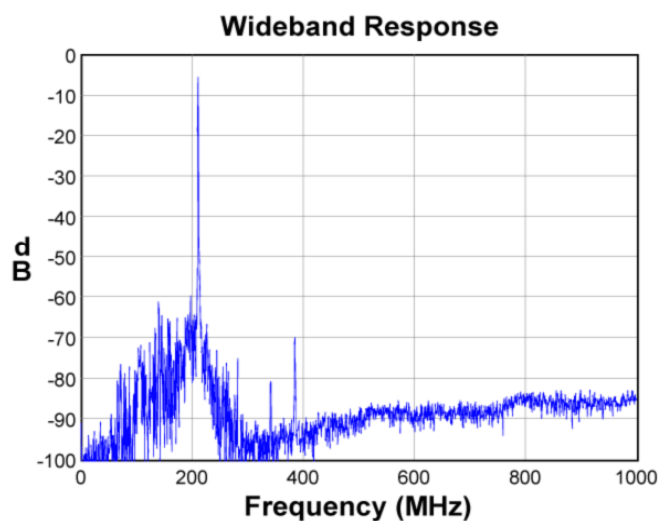
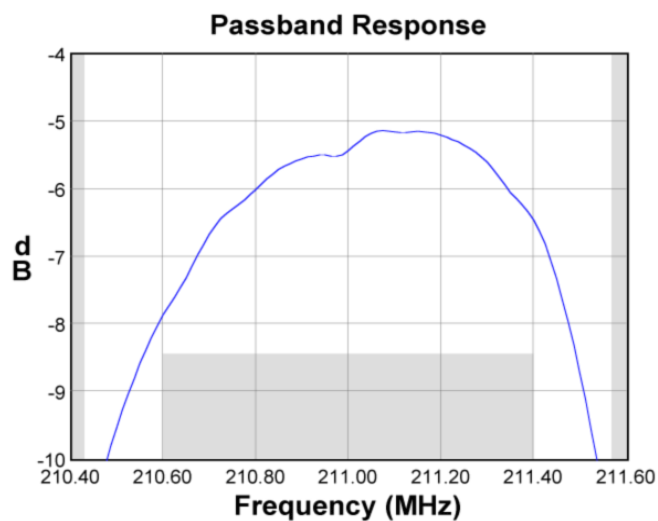
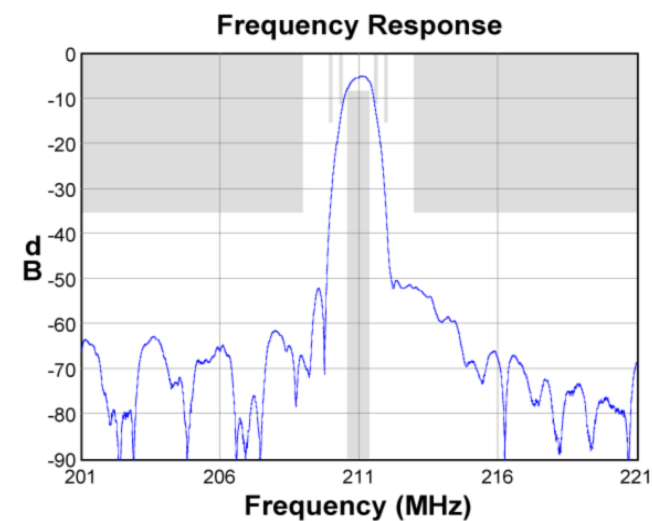
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### Test Circuit:

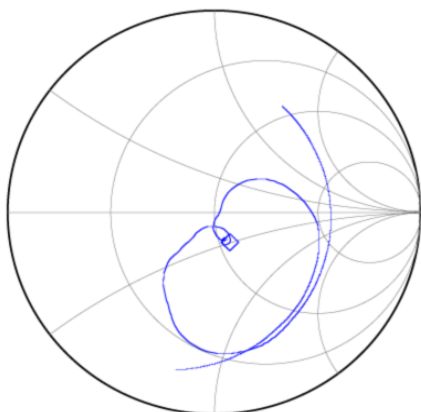
Actual matching values may vary due to PCB layout and parasitics



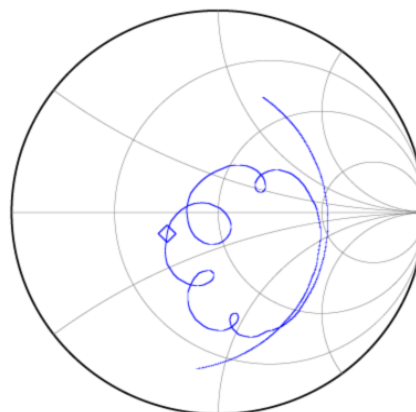
**Typical Performance (at room temperature)**



**Input Smith Chart**

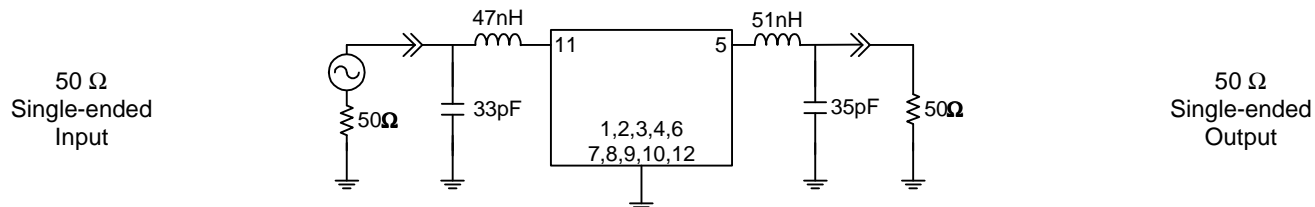


**Output Smith Chart**

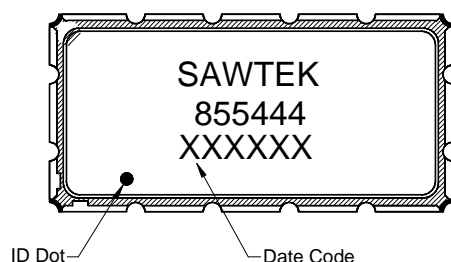


## Matching Schematics

Actual matching values may vary due to PCB layout and parasitics

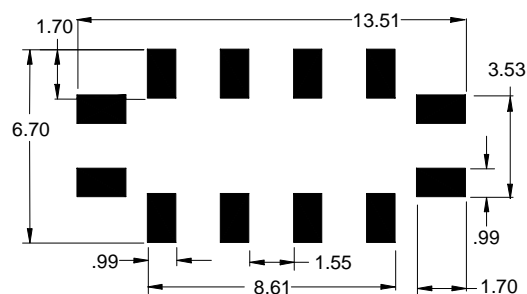


## Marking



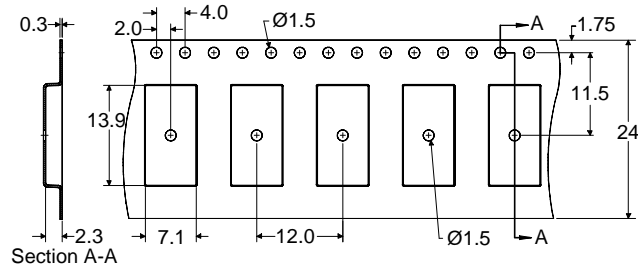
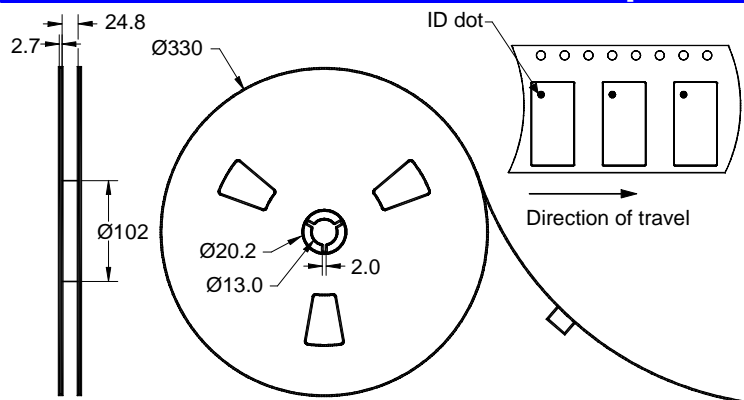
The date code consists of: day of the current year (Julian, 3 digits), last digit of the year (1 digit) and hour (2 digits)

## PCB Footprint



This footprint represents a recommendation only  
Dimensions shown are nominal in millimeters

## Tape and Reel



Dimensions shown are nominal in millimeters  
Packaging quantity: 2000 units/reel

## Maximum Ratings

Parameter	Symbol	Minimum	Maximum	Unit
Operating Temperature Range	T	-40	+85	°C
Storage Temperature Range	T <sub>stg</sub>	-40	+85	°C

## Important Notes

### Warnings

- Electrostatic Sensitive Device (ESD)
- Avoid ultrasonic exposure



### RoHS Compliance

- This product complies with EU directive 2002/95/EC (RoHS)



### Solderability

- Compatible with JESD22-B102, Pb-free process, 260C peak reflow temperature ([see soldering profile](#))

## Links to Additional Technical Information

[PCB Layout Tips](#)

[Qualification Flowchart](#)

[Soldering Profile](#)

[S-Parameters](#)

[RoHS Information](#)

[Other Technical Information](#)

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